

September 15, 2021

Notice of the Completion of Payment of the (Second) Issuance of New Shares through Third-Party Allotment at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers

In “(Change of a Disclosed Item) Notice of the (Second) Issuance of New Shares through Third-Party Allotment and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers” dated on July 15, 2021, we notified you of the increase of the total amount of new shares issued to a third party by the equity-method affiliate Hangzhou Semiconductor Wafer Co., Ltd. (hereinafter “CCMC”) from 3 billion yuan (about 51 billion yen) to 3.3 billion yuan (about 56.1 billion yen). This time, we have confirmed the completion of payment on August 31, 2021. For further information on this third-party allotment, please refer to “(Correction and Change of a Disclosed Item) Notice of the (Second) Issuance of New Shares through Third-Party Allotment and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers” released today. We apologize for not disclosing this matter on the date of final payment, because it took some time to check and examine payment vouchers.